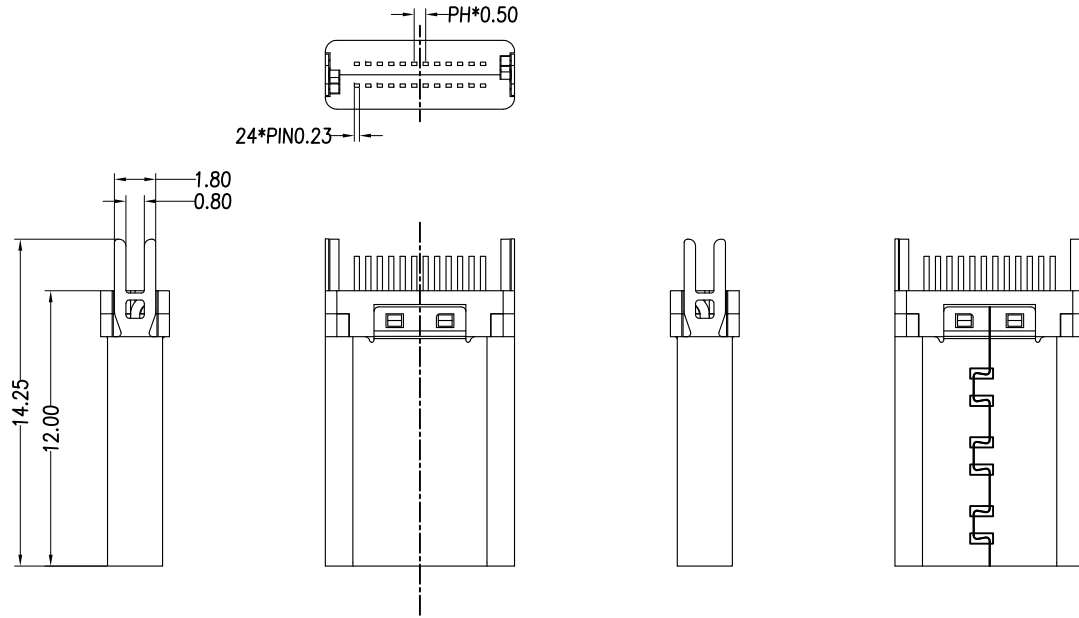


REV.	ECN. NO.	MODIFY. CONTENT	DATE



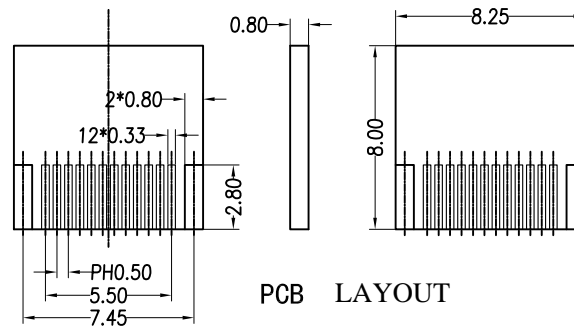
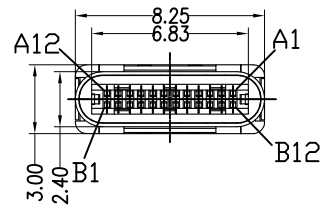
Material:

1. : Housing: High Temperature Thermoplastics, LCP
2. : Contact: Copper Alloy
3. : Shell: Copper Alloy
4. : Shell: Copper Alloy
5. : Shell: Copper Alloy

Finish:

1. : Contact: Plated gold in Mating Area; Tin On Solder Tails

Plating specification : 1U", 3U", 15U", 30U"



PCB LAYOUT

GENERAL TOLERANCE		FILE. NO.	CIU150514-1-C0	DRAWN	SCALE
X. ±0.25	X. ° ±5°	TITLE	USB 3.1 TYPE C Without pcb	CHECKED	UNITS
. XX ±0.20	. X ° ±2°			APPROVED	mm
. XX ±0.15	. XX ° ±1°	PART. NO.	1UM5210340RKA0	DATE	
. XXX ±0.05	. XXX ° ±0.5°	REV.	00		
SHEET	1/1	Q' TY	OVERSEA WIN TECHNOLOGY (HK) LIMITED		